

CLAIMS

1. A thermal dissipating element of a chip, comprising:
a top plate including a sink ; and
5 a side plate, said top plate curving and extendedly connecting to said side plate.

2. The thermal dissipating element according to claim 1,
wherein said sink contacts with said chip.

10 3. The thermal dissipating element according to claim 1,
wherein the shape of said sink is circular.

15 4. The thermal dissipating element according to claim 1,
wherein the shape of said sink is quadrilateral.

5. The thermal dissipating element according to claim 1,
wherein said sink further comprises a lump.

20 6. The thermal dissipating element according to claim 5,
wherein said lump contacts with a chip.

7. The thermal dissipating element according to claim 5,
wherein the shape of said lump is quadrilateral.

25 8. The thermal dissipating element according to claim 5,
wherein the shape of said lump is quadrilateral circular.

9. The thermal dissipating element according to claim 1,

wherein said lump is a silicon chip.

10. The thermal dissipating element according to claim 1,
further comprising a sole plate to extendedly connect to side
5 plate.

11. The thermal dissipating element according to claim 10,
said side plate and said sole plate including a plurality of
holes, said holes being formed between said side plate and said
10 sole plate.

12. The thermal dissipating element according to claim 10,
wherein said sole plate includes a plurality of cavities.

15 13. The thermal dissipating element according to claim 5,
wherein the material of said lump is metal.

14. The thermal dissipating element according to claim 13,
wherein the material of said lump is aluminum.

20 15. The thermal dissipating element according to claim 13,
wherein the material of said lump is copper.

16. A chip packaging element, comprising :
25 a substrate ;
a chip fastened on said substrate ; and
a thermal dissipating element of said chip, said thermal
dissipating element including a top plate, a side plate, and a
sole plate, said top plate curving and extendedly connecting to

said side plate, said side plate curving and extendedly connecting to said sole plate, said top plate having a sink, wherein said sole plate is fastened on said substrate.

5 17. The chip packaging element according to claim 16, wherein said sink is fastened on said chip, and said chip is fastened between said sink and said substrate.

10 18. The chip packaging element according to claim 17, wherein said sink contacts with all of said chip.

15 19. The chip packaging element according to claim 16, said sink further comprising a lump contacting between said sink and said chip, wherein said chip is fastened between said lump and said substrate.

20 20. The chip packaging element according to claim 19, wherein said lump is fastened on said sink by an adhesive with high thermal conductivity.